

Process description

A FOUP (front opening unified pod) is a special container in the semiconductor industry for safely transporting silicon wafers between the individual process steps in the cleanroom, such as lithography, CMP, etching and analytics.

A robot arm is used to remove the wafers for processing. The FOUPs are then transported via ceiling conveyors to the next process tool. (Dust) particles may form and deposit on the wafers due to the frequent transport operations and different process steps.

Regular cleaning of the FOUPs is therefore essential. It is particularly important to efficiently remove particles and airborne molecular contamination (AMC).

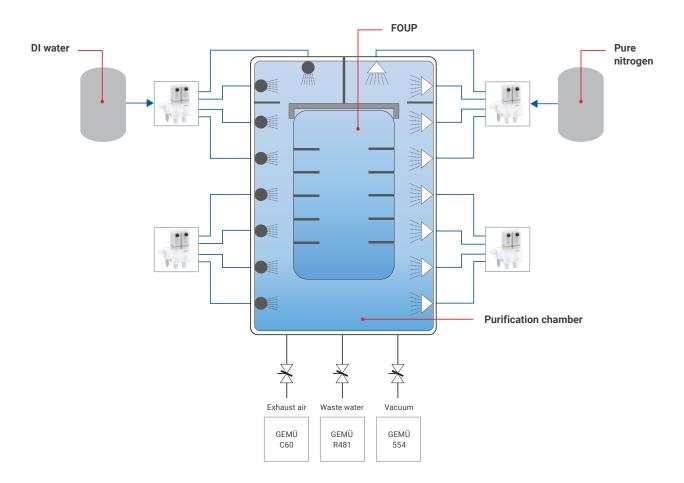
The task

Requirements for components used in the application:

- Handling of media in various aggregate states (gases and DI water)
- All components in the medium feed must be produced from ultra-pure fluoroplastics
- Reliable mixing of the cleaning media used (different temperatures and aggregate states, etc.) through continuous checking of the operating parameters
- Compact component design due to use in space-critical environments



Diagrammatic process visualization



Suitable GEMÜ products

